



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE8458G V33			<b>Issued</b>	19. July 2018			
<b>MA#</b>	MA001191168							
<b>Package</b>	PG-DSO-8-16			<b>Weight*</b>	83.61 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.909	4.68	4.68	46750	46750
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8578	
wire	non noble metal	copper	7440-50-8	29.121	34.83	35.74	348319	357433
	noble metal	gold	7440-57-5	0.121	0.14	0.14	1445	1445
	encapsulation	organic material	carbon black	1333-86-4	0.093	0.11		1114
plastics		epoxy resin	-	4.285	5.13		51256	
	inorganic material	silicondioxide	60676-86-0	42.200	50.48	55.72	504757	557127
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9734	9734
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7778	7778
glue	plastics	acrylic resin	-	0.363	0.43		4341	
	noble metal	silver	7440-22-4	1.287	1.54	1.97	15392	19733
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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